
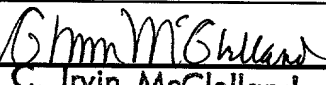


Jc715 U.S. PTO  
09/22/00

Jc916 U.S. PTO  
09/22/00

<b>UTILITY PATENT APPLICATION TRANSMITTAL</b> <small>(Only for new nonprovisional applications under 37 CFR 1.53(b))</small>	Attorney Docket No.	197399US2
	First Inventor or Application Identifier	Masahito KOBAYASHI, et al.
	Title	PROBING METHOD AND PROBING APPARATUS

<b>APPLICATION ELEMENTS</b> <i>See MPEP chapter 600 concerning utility patent application contents</i>	<b>ADDRESS TO:</b> Assistant Commissioner for Patents Box Patent Application Washington, DC 20231
<p>1. <input checked="" type="checkbox"/> Fee Transmittal Form (e.g. PTO/SB/17) (Submit an original and a duplicate for fee processing)</p> <p>2. <input checked="" type="checkbox"/> Specification Total Pages <b>39</b></p> <p>3. <input checked="" type="checkbox"/> Drawing(s) (35 U.S.C. 113) Total Sheets <b>5 (Formals)</b></p> <p>4. <input checked="" type="checkbox"/> Oath or Declaration Total Pages <b>4</b></p> <p>a. <input type="checkbox"/> Newly executed (original)</p> <p>b. <input type="checkbox"/> Copy from a prior application (37 C.F.R. §1.63(d)) (for continuation/divisional with box 15 completed)</p> <p>i. <input type="checkbox"/> <b>DELETION OF INVENTOR(S)</b> Signed statement attached deleting inventor(s) named in the prior application, see 37 C.F.R. §1.63(d)(2) and 1.33(b).</p> <p>5. <input type="checkbox"/> Incorporation By Reference (usable if box 4B is checked) The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied under Box 4B, is considered to be part of the disclosure of the accompanying application and is hereby incorporated by reference therein.</p>	<b>ACCOMPANYING APPLICATION PARTS</b>
<p>6. <input checked="" type="checkbox"/> Assignment Papers (cover sheet &amp; document(s))</p> <p>7. <input type="checkbox"/> 37 C.F.R. §3.73(b) Statement (when there is an assignee) <input type="checkbox"/> Power of Attorney</p> <p>8. <input type="checkbox"/> English Translation Document (if applicable)</p> <p>9. <input checked="" type="checkbox"/> Information Disclosure Statement (IDS)/PTO-1449 <input checked="" type="checkbox"/> Copies of IDS Citations (1)</p> <p>10. <input type="checkbox"/> Preliminary Amendment</p> <p>11. <input checked="" type="checkbox"/> White Advance Serial No. Postcard</p> <p>12. <input type="checkbox"/> Small Entity Statement(s) <input type="checkbox"/> Statement filed in prior application. Status still proper and desired.</p> <p>13. <input checked="" type="checkbox"/> Certified Copy of Priority Document(s) (1) (if foreign priority is claimed)</p> <p>14. <input checked="" type="checkbox"/> Other: Notice of Priority, List of Related Cases, Statement of Relevancy</p>	
<p>15. If a CONTINUING APPLICATION, check appropriate box, and supply the requisite information below:</p> <p><input type="checkbox"/> Continuation <input type="checkbox"/> Divisional <input type="checkbox"/> Continuation-in-part (CIP) of prior application no.: Prior application information: Examiner: Group Art Unit:</p>	
<p>16. Amend the specification by inserting before the first line the sentence:</p> <p><input type="checkbox"/> This application is a <input type="checkbox"/> Continuation <input type="checkbox"/> Division <input type="checkbox"/> Continuation-in-part (CIP) of application Serial No. Filed on</p> <p><input type="checkbox"/> This application claims priority of provisional application Serial No. Filed</p>	
<p align="center"><b>17. CORRESPONDENCE ADDRESS</b></p> <p align="center"> <b>22850</b> (703) 413-3000 FACSIMILE: (703) 413-2220</p>	

Name:	Marvin J. Spivak	Registration No.:	24,913
Signature:		Date:	9/22/00
Name:	C. Irvin McClelland	Registration No.:	21,124

Docket No. 197399US2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTOR(S) Masahito KOBAYASHI, et al.

\* SERIAL NO: New Application

FILING DATE: Herewith

\* FOR: PROBING METHOD AND PROBING APPARATUS

FEE TRANSMITTAL

ASSISTANT COMMISSIONER FOR PATENTS

WASHINGTON, D.C. 20231

FOR	NUMBER FILED	NUMBER EXTRA	RATE	CALCULATIONS
TOTAL CLAIMS	23 - 20 =	3	× \$18 =	\$54.00
INDEPENDENT CLAIMS	6 - 3 =	3	× \$78 =	\$234.00
■ MULTIPLE DEPENDENT CLAIMS (If applicable)			+ \$260 =	\$260.00
□ LATE FILING OF DECLARATION			+ \$130 =	\$0.00
BASIC FEE				\$690.00
TOTAL OF ABOVE CALCULATIONS				\$1,238.00
□ REDUCTION BY 50% FOR FILING BY SMALL ENTITY				\$0.00
□ FILING IN NON-ENGLISH LANGUAGE			+ \$130 =	\$0.00
■ RECORDATION OF ASSIGNMENT			+ \$40 =	\$40.00
TOTAL				\$1,278.00

- Please charge Deposit Account No. 15-0030 in the amount of A duplicate copy of this sheet is enclosed.
- A check in the amount of \$1,278.00 to cover the filing fee is enclosed.
- The Commissioner is hereby authorized to charge any additional fees which may be required for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

Date: 9/28/02

C. Irvin McClelland  
Marvin J. Spivak  
Registration No. 24,913



22850

C. Irvin McClelland  
Registration Number 21,124

Tel. (703) 413-3000  
Fax. (703) 413-2220  
(OSMMN 11/98)

# TITLE OF THE INVENTION

## PROBING METHOD AND PROBING APPARATUS

### CROSS-REFERENCE TO RELATED APPLICATIONS

This application is based upon and claims the  
5 benefit of priority from the prior Japanese Patent  
Application No. 11-285139, filed October 6, 1999,  
the entire contents of which are incorporated herein  
by reference.

### BACKGROUND OF THE INVENTION

10 The present invention relates to a probing method  
and a probing apparatus, and more specifically, to  
a probing method and a probing apparatus with high  
reliability, in which a load applied to a main chuck  
carrying an object of inspection thereon by probes  
15 is measured when the main chuck is overdriven to the  
probes, so that a steady load can always be applied to  
the main chuck in accordance with the measured value.

As shown in FIG. 8, a probing apparatus 10 for  
checking integrated circuits on a wafer for electrical  
20 properties, for example, is provided with a loading  
chamber 11, probing chamber 12, controller 13, and  
display unit 14. In the loading chamber 11, wafers W  
stored in a cassette C are delivered one after another  
and transported to the probing chamber 12. The probing  
25 chamber 12 adjoins the loading chamber 11. Integrated  
circuits formed on each wafer W that is transported  
from the loading chamber 11 are inspected in the

probing chamber 12. The controller 13 controls the chambers 11 and 12. The display unit 14 doubles as a control panel for operating the controller 13.

5 The loading chamber 11 is provided with a pair of tweezers 15 for use as a transportation mechanism for the wafers W. The tweezers 15 moves back and forth in the horizontal direction and rotates forward and reversely, thereby delivering the wafers W in the cassette C one after another and transporting them  
10 into the probing chamber 12. A sub-chuck 16 for pre-aligning each wafer W is provided near the tweezers 15. As the sub-chuck 16 receives each wafer W from the tweezers 15 and rotates forward or reversely in a  $\theta$ -direction, it pre-aligns the wafer W on the basis of  
15 its orientation flat.

The probing chamber 12 is provided with a main chuck 17 that carries each wafer W thereon. The main chuck 17 is moved in X- and Y-directions by means of X- and Y-stages 18, 19, respectively, and moved in Z-  
20 and  $\theta$ -directions by means of built-in drive mechanisms. Alignment means 20 is provided in the probing chamber 12. The alignment means 20 serves to align each wafer W with the probes. The alignment means 20 includes an alignment bridge 22 having first image-pickup  
25 means (e.g., CCD camera) 21 for imaging the wafer W, a pair of guide rails 23 for guiding the bridge 22 in reciprocation in the Y-direction, and second

image-pickup means (e.g., CCD camera, not shown)  
attached to the main chuck 17. A probe card is  
provided on the top surface of the probing chamber 12.  
On the upper surface of the probe card, a test hed is  
5 connected electrically to the card by means of a  
connecting ring. A test signal from a tester 34 (see  
FIG. 1) is transmitted to the probe card via the test  
hed and the connecting ring, and further transmitted  
from the probe card to the wafer W. The object of  
10 inspection is checked for electrical properties in  
accordance with the test signal.

In inspecting the integrated circuits formed on  
each wafer W, the tweezers 15 takes out one of the  
wafers W from the cassette C. While the wafer W is  
15 being transported to the probing chamber 12, it is  
pre-aligned on the sub-chuck 16. Thereafter, the  
tweezers 15 delivers the wafer W to the main chuck 17  
in the probing chamber 12. The alignment bridge 22  
moves to the center of the probe card. The main chuck  
20 17 moves to the position under the first image-pickup  
means 21 of the bridge 22, and the wafer on the chuck  
17 is aligned with the probe card by means of the  
first image-pickup means 21 and the second image-pickup  
means. As the main chuck 17 moves in the X- and  
25 Y-directions, the wafer W is subjected to index feed.  
As the chuck 17 ascends in the Z-direction, the  
electrodes of the integrated circuits are brought

into contact with probes. When the main chuck 17 is overdriven, the integrated circuits on the wafer W are checked for electrical properties with their electrodes electrically in contact with the probes.

5           In the case of a wafer W with a diameter of 200 mm or less, as shown in FIG. 9A, the wafer W on the main chuck 17 ascends from the position indicated by dashed line to the position indicated by full line as the main chuck 17 is overdriven. As indicated by full line in  
10       FIG. 9A, the wafer W rises in the Z-direction without substantially tilting from its horizontal position. As this is done, each probe 24A of a probe card 24 is elastically raised from the position of dashed line to the position of full line of FIG. 9A. The tip of the  
15       probe 24A moves from a starting point S to an ending point E, as indicated by thick line. The plane distance covered by the tip that moves from the starting point S to the ending point E, as indicated by hatched arrow in FIG. 9B, is within the area of  
20       an electrode pad P of each integrated circuit. Thus, the probe 24A and the electrode pad P are brought electrically into contact with each other, whereupon the integrated circuit is inspected.

25           In the case of a wafer W with a diameter of 300 mm, the wafer size is too large, and besides, the integrated circuits are hyperfine, and electrode pads are arranged at narrow pitches. The number of

pins of the probe card is increased (e.g., to 2,000) correspondingly. A load from about 2,000 probes 24A that acts on the main chuck 17 when the chuck is overdriven is as heavy as, for example, more than 10 kg to 20 kg. Accordingly, an unbalanced load that is generated when the wafer W is overdriven from the position indicated by dashed line in FIG. 10A so that it touches the probes 24A causes the rotating shaft (not shown) of the main chuck 17 to bend.

In consequence, the wafer W is tilted for about 20 to 30  $\mu\text{m}$ , for example, as indicated by full line in FIG. 10A, and deflected outward from its original raised position. As this is done, the tip of each probe 24A is elastically raised from the position indicated by dashed line to the position indicated by full line of FIG. 10A, and moves along a track (indicated by thick line in FIG. 10A) that is longer than the one shown in FIG. 9A. Although the starting point S of the tip is situated in the same position as the one shown in FIG. 9A, the ending point E is located outside the area of the electrode pad P, as indicated by hatched arrow in FIG. 10B. Thus, test signals cannot be transmitted from the probes 24A to the electrode pads P, so that the reliability of the inspection is lowered.

In Jpn. Pat. Appln. KOKAI Publication  
No. 11-30651, the inventor hereof proposed a probing

method and a probing apparatus in which dislocation  
of probes attributable to contact load is corrected  
three-dimensionally. According to this technique, the  
probes estimate a distortion of a main chuck in the  
position where the probes are in contact with a wafer,  
in accordance with known data, such as information  
(outside diameter, material, etc.) on the main chuck,  
information (outside diameter, number of chips, etc.)  
on the wafer, and information (probe tip area, number  
of probes, etc.) on a probe card. Based on the  
estimated value, the position where the probes are  
in contact with the wafer is corrected three-  
dimensionally.

#### BRIEF SUMMARY OF THE INVENTION

According to the probing method and the probing  
apparatus described in Jpn. Pat. Appln. KOKAI  
Publication No. 11-30651, a load (needle pressure) in  
the contact position of the probes is estimated in  
accordance with the contact position for overdrive  
operation and a given overdrive, the distortion of the  
main chuck is estimated according to the estimated  
load, and the contact position of the probes is  
three-dimensionally corrected in accordance with the  
estimated distortion. If the estimated load and  
an actual load are inconsistent, therefore, the  
three-dimensional correction of the contact position  
of the probes may possibly be wrong. Further, the



conventional probing method and apparatus use a mechanism that obtains the given overdrive by driving the Z-axis. On the other hand, the distance between the probe tip and the wafer W changes due to deformation of the probe card with time or thermal expansion or contraction of the card during inspection. Since the overdrive of the main chuck is fixed, however, a constant contact load cannot be obtained.

The object of the present invention is to solve the above problems.

An object of the present invention is to bring probes and electrode pads of an object of inspection accurately into contact with one another under a steady load even if a probe card is deformed from various causes or expanded or contracted by any thermal effect.

Another of the of the invention is provide a probing method and a probing apparatus, in which probes and electrode pads of an object of inspection can be brought accurately into contact with one another if a main chuck is tilted by an unbalanced load during overdrive operation, so that high-accuracy inspection can be enjoyed.

Additional objects and advantages of the invention will be set forth in the description which follows, and in part will be obvious from the description, or may be learned by practice of the invention. The objects and advantages of the invention may be realized and

002260" 205/9960

obtained by means of the instrumentalities and combinations particularly pointed out hereinafter.

In a first aspect of the present invention, there is provided a probing method comprising steps of:

5 moving a main chuck to align an object of inspection on the main chuck with probes of a probe card located over the main chuck; moving the main chuck toward the probe card, thereby bringing electrodes of the object of inspection into contact with the probes; overdriving  
10 the main chuck toward the probe card while measuring a load applied to the object of inspection by contact with the probes and controlling the movement of the main chuck in accordance with the measured load; and inspecting electrical properties of the object of  
15 inspection by means of the probe.

Preferably, in this probing method, the control of the movement of the main chuck is control of an overdrive based on the measured load, such that the load has a given value.

20 Preferably, in this probing method, the control of the movement of the main chuck further includes steps of obtaining a distortion of the main chuck in accordance with the measured load and correcting at least one of dislocations between the object of  
25 inspection and the probe in X-, Y-, and  $\theta$ -directions in accordance with the distortion.

Preferably, in this probing method, the

measurement of the load applied to the object of inspection by contact with the probes includes steps of locating a polishing mechanism right under the probes, the polishing mechanism including a polish plate to be used to polish the tip of the probes; moving the located polishing mechanism toward the probe card, thereby bringing the polish plate into contact with the probes; overdriving the polishing mechanism toward the probe card; and measuring a load applied to the polish plate by the probes by means of a pressure sensor attached to the polishing mechanism during the overdrive operation.

In a second aspect of the present invention, there is provided a probing method comprising steps of: moving a main chuck in X-, Y-, and  $\theta$ -directions to align an object of inspection on the main chuck with probes of a probe card located over the main chuck; moving the main chuck in a Z-direction, thereby bringing electrodes of the object of inspection into contact with the probes; overdriving the main chuck toward the probe card while measuring a load applied to the object of inspection by contact with the probes by means of a sensor and controlling the movement of the main chuck in accordance with the measured load; and inspecting electrical properties of the object of inspection by means of the probes.

Preferably, in this probing method, the sensor is

located on at least one of the lower part of the main chuck and between an LM guide and an XY-stage on which the main chuck is set.

Preferably, in this probing method, the control of the movement of the main chuck is control of an overdrive of the main chuck.

Preferably, in this probing method, the control of the movement of the main chuck includes steps of obtaining a distortion of the main chuck in accordance with the measured load and correcting at least one of dislocations between the object of inspection and the probes in the X-, Y-, and  $\theta$ -directions in accordance with the distortion.

In a third aspect of the invention, there is provided a probing method in which a main chuck is moved in X-, Y-, and  $\theta$ -directions to align an object of inspection on the main chuck with probes of a probe card located over the main chuck, the main chuck is moved in a Z-direction so that electrodes of the object of inspection are brought into contact with the probes, the main chuck is overdriven toward the probe card, and electrical properties of the object of inspection are inspected by means of the probes, the probing method comprising steps of: locating a polishing mechanism right under the probes, the polishing mechanism including a polish plate to be used to polish the tip of the probes; moving the located polishing mechanism

002250" 205/3950  
toward the probe card, thereby bringing the polish  
plate into contact with the probes; overdriving the  
polishing mechanism toward the probe card; measuring  
a load applied to the polish plate by the probes by  
5 means of a pressure sensor during the overdrive  
operation; and controlling the movement of the main  
chuck in accordance with the measured load.

Preferably, in this probing method, the sensor is  
set on the polishing mechanism.

10 Preferably, in this probing method, the control of  
the movement of the main chuck is control of an  
overdrive of the main chuck.

Preferably, this probing method comprises steps of  
obtaining a distortion of the main chuck in accordance  
15 with the measured load and correcting at least one of  
dislocations between the object of inspection and the  
probes in the X-, Y-, and  $\theta$ -directions in accordance  
with the distortion.

Preferably, in this probing method, the control  
20 of the overdrive of the main chuck includes steps  
of obtaining a distortion of the polish plate in  
accordance with the relation between the load applied  
to the polish plate and the distortion of the polish  
plate and the load applied to the polish plate and  
25 measured by means of the pressure sensor; obtaining the  
spring constant of the probes from the distortion and  
an overdrive of the polish plate; obtaining the spring

constant of the main chuck in accordance with the  
spring constant of the probes and the relation between  
the load and a distortion of the main chuck; obtaining  
a load applied to the main chuck by the probes in  
5 accordance with the spring constant of the main chuck  
and the relation between the spring constant and the  
overdrive of the main chuck; and controlling the  
overdrive of the main chuck in accordance with the  
obtained load.

10 Preferably, this probing method further comprises  
steps of obtaining a distortion of the main chuck in  
accordance with the load measured by means of the  
pressure sensor and correcting dislocations between  
the object of inspection and the probe in X- and  
15 Y-directions in accordance with the distortion.

In a fourth aspect of the invention, there is  
provided a probing apparatus comprising: a main chuck  
carrying an object of inspection thereon; a probe card  
having a plurality of probes and located over the main  
20 chuck; a drive mechanism for moving the main chuck in  
X-, Y-, Z-, and  $\theta$ -directions; a pressure sensor adapted  
to measure a load applied to the object of inspection  
by the probes when the drive mechanism moves the main  
chuck toward the probe card so that the object of  
25 inspection on the main chuck is brought into contact  
with probes; and a controller for controlling the  
movement of the main chuck in accordance with a

position where the probes touches the object of inspection and the load measured by means of the pressure sensor.

002260" 205/9960

5 In a fifth aspect of the invention, there is provided a probing apparatus comprising: a main chuck carrying an object of inspection thereon; a probe card having a plurality of probes and located over the main chuck; a drive mechanism for moving the main chuck in X-, Y-, Z-, and  $\theta$ -directions; a pressure sensor adapted to measure a load applied to the object of inspection by the probes when the drive mechanism moves the main chuck toward the probe card so that the object of inspection on the main chuck is brought into contact a probes; and a controller for obtaining a distortion of the main chuck in accordance with a position where the probes touches the object of inspection and the load measured by means of the pressure sensor.

10

15

20 Preferably, the controller of this probing apparatus controls an overdrive in accordance with the measured load so that the load has a given value.

25 Preferably, the controller of this probing apparatus corrects at least one of dislocations between the object of inspection and the probes in the X-, Y-, and  $\theta$ -directions in accordance with the distortion.

In a sixth aspect of the invention, there is provided a probing apparatus comprising: a main chuck carrying an object of inspection thereon; a polishing

mechanism having a polish plate and attached to the  
main chuck; a probe card having a plurality of probes  
and located over the main chuck; a drive mechanism for  
moving the main chuck in X-, Y-, Z-, and  $\theta$ -directions;  
5 a pressure sensor adapted to measure a load applied to  
the polish plate of the polishing mechanism attached to  
the main chuck by the probes when the drive mechanism  
moves the main chuck toward the probe card so that  
the polish plate is brought into contact with probes;  
10 and a controller for controlling the drive mechanism,  
the controller including a mechanism for obtaining  
the spring constant of the probes in accordance with  
the load measured by means of the pressure sensor,  
obtaining the spring constant of the stage in  
15 accordance with the relation between the load and  
a distortion of the main chuck, and obtaining a load  
applied in the position where the probes touch the main  
chuck in accordance with the relation between the  
respective spring constants of the probes and the main  
20 chuck and an overdrive of the main chuck.

#### BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWING

The accompanying drawings, which are incorporated  
in and constitute a part of the specification, illust-  
rate presently preferred embodiments of the invention,  
25 and together with the general description given above  
and the detailed description of the preferred embodi-  
ments given below, serve to explain the principles of



the invention.

FIG. 1 is a side view showing the principal part of one embodiment of a probing apparatus according to the present invention;

5           FIG. 2 is a block diagram showing the principal part of the probing apparatus shown in FIG. 1;

FIG. 3 is a view illustrating the operation of the principal part of the probing apparatus shown in FIG. 2;

10           FIG. 4 is a diagram for illustrating the operation of a wafer on a main chuck shown in FIG. 2 and a probe;

          FIGS. 5A and 5B illustrate the operation of the wafer and the probe shown in FIG. 4, in which FIG. 5A is a diagram for illustrating the respective behaviors of the wafer and the probe, and FIG. 5B is a diagram for illustrating the trace of the tip of the probe on an electrode pad;

          FIG. 6 is a side view showing another embodiment of the probing apparatus according to the invention;

20           FIG. 7 is a block diagram showing the principal part of the probing apparatus shown in FIG. 6;

FIG. 8 is a cutaway perspective view of a conventional probing apparatus;

          FIG. 9A is a partially enlarged conceptual diagram showing the relation between a main chuck and a probe established when the main chuck is overdriven under a single-pin probe card;

FIG. 9B is a diagram for illustrating the relation between an electrode pad and the trace of the tip of the probe in the state shown in FIG. 9A;

FIG. 10A is a partially enlarged conceptual  
5 diagram showing the relation between the main chuck and the probe established when the main chuck is overdriven under a multi-pin probe card; and

FIG. 10B is a diagram for illustrating the relation between the electrode pad and the trace of  
10 the tip of the probe in the state shown in FIG. 10A.

#### DETAILED DESCRIPTION OF THE INVENTION

A probing method and a probing apparatus according to the present invention can be used to check integrated circuits on a wafer for electrical properties.  
15 Alternatively, however, the invention may be applied to the inspection of the electrical properties of general electronic components such as LCD's.

In order to explain the present invention more specifically and definitely, there will be described  
20 a case in which the invention is applied to the inspection of the electrical properties of integrated circuits formed on a wafer.

The invention will be described in connection with embodiments shown in FIGS. 1 to 7, in which like  
25 reference numerals refer to like or equivalent portions throughout the several views.

A probing apparatus 10 according to an embodiment

of the invention, like the probing apparatus shown in FIG. 8, may be provided with a loading chamber 11 and a probing chamber 12. Alternatively, however, the loading chamber 11 and the probing chamber 12 may be arranged separately. The tweezers 15 and a sub-chuck 16 are arranged in the loading chamber 11. Wafers W in a cassette C are transported one after another by means of the tweezers 15. In this process of transportation, each wafer W can be pre-aligned by means of the sub-chuck 16. A main chuck 17, which is movable in Z- and  $\theta$ -directions, X-stage 18, Y-stage 19, and alignment means 20 are arranged in the probing chamber 12. As the main chuck 17 moves in X-, Y-, Z-, and  $\theta$ -directions under the control of a controller 13, it aligns the wafer W thereon with a probe card in conjunction with the alignment means 20. After the alignment, the main chuck ascends in the Z-direction, whereupon integrated circuits formed on the wafer W is checked for electrical properties with its electrodes electrically in contact with a probe 24A.

According to the present embodiment, a pressure sensor (e.g., load cell) 31 is provided for the measurement of load. Although the pressure sensor 31 is located between the main chuck 17 and the X-table 18 in the arrangement shown in FIG. 1, the location of the sensor is not limited to this position. For example, the sensor 31 may be located between an X, Y-table and

an LM guide 40 (FIG. 8). The pressure sensor 31 is used to measure load from the probe 24A that acts on the wafer W on the main chuck 17. As shown in FIG. 2, the sensor 31 is connected to the controller 13. The controller serves to control the movement of the main chuck in accordance with a signal measured by means of the pressure sensor 31. By this control, the overdrive can be adjusted so that the load from the probe 24A that acts on the wafer W is constant. Alternatively, under this control, the distortion of the main chuck may be obtained from the measured load so that at least one of dislocations between the object of inspection and the probe in the X-, Y-, and  $\theta$ -directions can be corrected in accordance with the distortion.

The adjustment of the overdrive and correction of the dislocation between the object of inspection and the probe can be carried out in combination with each other.

As shown in FIG. 2, the controller 13 can comprises first storage means 131 for storing data such as wafer information on the wafers W, card information on the probe card, etc., second storage means 132 for storing data such as control programs for the probing apparatus, main chuck information on the main chuck 17, and a central processing unit (hereinafter referred to as "CPU") 133. The CPU 133 can read the individual pieces of information stored in the first and second

storage means 131 and 132 and carry out processes based on predetermined programs.

The wafer information may include parameters such as the location of each chip, chip size, position of the center of gravity of the chip, number of electrode pads, pitches between the electrode pads, etc. The card information may include parameters such as the number of probe needles (number of pins), location of the probe needles, material and properties of the probe needles, etc. The main chuck information may include parameters such as the mechanical strength of the rotating shaft of the main chuck 17, outside diameter and load-distortion data of the chuck 17, etc. The load-distortion data may be defined as data that are indicative of load on a typical point on the upper surface of main chuck 17 and the relation between the load and the distortion of the chuck 17. The CPU 133 includes the measured load (needle pressure) of the pressure sensor 31 and distortion processing means 133A. The processing means 133A obtains the distortion of the main chuck 17 for a probe contact position in an overdrive mode in accordance with the load-distortion data of the main chuck and the wafer information. The distortion processing means 133A is used to obtain the distortion of the main chuck 17 in accordance with the measured load of the pressure sensor 31 for the contact position of the probe 24A and the load-distortion data.

As shown in FIG. 2, input means (e.g., keyboard, etc.) 25 and the display unit 14 are connected to the controller 13. Necessary data for various inspections, such as the wafer information and main chuck information, are inputted by means of the input means 25. The input data are recognized by the display unit 14. A drive mechanism 26 is connected to the controller 13. The drive mechanism 26 serves to drive the main chuck 17.

The following is a description of the probing method and the operation of the probing apparatus. Before the wafers W are inspected, the wafer information and the card information are inputted by the input means 25. The input data are recognized on a display screen. If the input data are correct, they are stored in the first storage means 131. The wafers W in each cassette are fed into the probing apparatus 10. After each wafer W is pre-aligned in the loading chamber, it is fed onto the main chuck 17 in the probing chamber. In the probing chamber, the wafer W is aligned with the probe 24A by means of the alignment means. The electrical properties of each chip of the wafer W are successively inspected by means of the probe 24A.

In the inspection of each chip, the probing apparatus 10 is actuated in accordance with programs for the probing method of the invention read from the

second storage means 132 by means of the CPU 133.

The first one of the integrated circuits on the wafer W to be measured is settled. The CPU 133 subjects the main chuck 17 to index feed, whereupon the integrated circuits on the wafer W are inspected in succession.

In the inspection of each integrated circuit, the main chuck 17 is overdriven after it ascends to a position where the wafer W and the probe 24A are in contact with each other. During the overdrive operation, the pressure sensor 31 measures load (needle pressure) between the probe 24A and the wafer W. The overdrive is monitored in accordance with the measured load.

When a preset load value is measured by means of the pressure sensor 31, the controller 13 stops the operation of the drive mechanism 26, thereby stopping the main chuck 17, whereupon a fixed overdrive can be secured. The main chuck 17 tilts as it is subjected to an unbalanced load during the overdrive operation. FIG. 3 exaggeratingly shows the tilted state of the main chuck. In FIG. 3, arrows indicate a contact load and its reaction force, individually.

In the conventional probing method, the overdrive is controlled by fixing the ascent of the main chuck 17 in the Z-direction. Accordingly, the position of the tip of the probe 24A is vertically deviated from its reference position, due to thermal expansion of the probe card 24 that is caused when the wafer W is heated

during the inspection, contraction of the card 24 that is caused when the wafer W is cooled, or deformation (exaggerated in FIG. 3) of the card 24 with time.

Thus, the conventional probing method cannot secure an  
5 overdrive that matches the actual distance between the probe 24A and the wafer W. In consequence, the contact load and the tip position fluctuate depending on the spot of contact of the probe, so that it is hard to effect steady inspection.

10 According to the present embodiment, the pressure sensor measures the contact load (needle pressure) between the probe 24A and the wafer W. Since the overdrive is controlled according to this measured load, steady inspection can be carried out under a  
15 constant contact load (needle pressure) without being influenced by any thermal effect or deformation of the probe card 24 with time.

According to the present embodiment, the contact position of the probe 24A can be corrected three-  
20 dimensionally during the overdrive operation. The method of the present embodiment, unlike a probing method proposed in Jpn. Pat. Appln. KOKAI Publication No. 9-306516, can three-dimensionally correct the contact position of the probe 24A in accordance with  
25 the measured load from the probe 24A that acts on the main chuck 17. According to the method described in Jpn. Pat. Appln. KOKAI Publication No. 9-306516,



the contact load produced by the probe is estimated, distortion of the main chuck 17 is obtained from the estimated value, and the contact position of the probe 24A is three-dimensionally corrected in accordance with the distortion.

As the wafer W, which is in contact with the probe 24A in the position indicated by dashed line in FIG. 4, is overdriven to the position indicated by full line, it is subjected to an unbalanced load from the probe 24A, and the main chuck 17 is tilted by the unbalanced load. In consequence, the wafer W tilts outward from its original position, and the a starting point S of the tip of the probe 24A is urged to move in the direction indicated by arrow A in FIG. 4. According to the present embodiment, the distortion processing means 133A obtains distortion for the load measured by means of the pressure sensor 31, in accordance with the measured load and the load-distortion data. Based on this distortion, the movement of the main chuck 17 is corrected by means of the drive mechanism 26, and the wafer W moves in the direction of arrow B in FIG. 4. Thus, the moving direction of the main chuck 17 is corrected according to the load measured by means of the pressure sensor 31. Accordingly, the wafer W ascends as if it were kept horizontal, and the tip of the probe 24A is vertically lifted upward, as indicated by arrow C. In consequence, the probe tip moves on

a track that is hardly different from the track for the case where the wafer W is lifted horizontally (see FIG. 9). As shown in FIG. 5B, an ending point E of the tip remains in an electrode pad P. In consequence, the probe 24A comes securely into contact with the given electrode pad P, so that the inspection of the integrated circuits can be carried out securely and steadily.

According to the present embodiment, as described above, the load that is produced as the probe 24A touches the wafer W is measured by means of the pressure sensor 31 when the main chuck 17 is overdriven under the control of the controller 13. The overdrive of the main chuck 17 or the position of the wafer W relative to the position of the probe is corrected according to the measured load. If the probe card 24 is deformed by any thermal effect or use, therefore, the probe 24A can touch the wafer W under a constant needle pressure. Alternatively, the probe 24A can steadily touch a given position on the wafer W. In consequence, highly reliable inspection can be carried out.

If the diameter of the wafer W and the number of pins of the probe card 24 are increased, moreover, the main chuck 17 is tilted by the unbalanced load during the overdrive operation. However, the pressure sensor 31 can measure the unbalanced load, and the contact

position of the probe 24A can be corrected according to the measured load and the load-distortion data of the main chuck 17. In consequence, the position of the main chuck can be highly accurately corrected without being influenced by deformation that is attributable to heat from the probe card 24 or use. As shown in FIG. 5B, the probe 24A can be securely brought into electrical contact with the electrode pad P of each integrated circuit in any spot on the wafer W, so that high-reliability inspection can be carried out securely.

FIGS. 6 and 7 show another embodiment of the present invention. According to the present embodiment, as shown in FIG. 6, a support arm 32 extends horizontally from a straight trunk portion of a main chuck 17. The arm 32 is provided with a polishing mechanism 33 for polishing a probe 24A. The mechanism 33 includes a polish plate 33A for polishing the probe 24A and a support block 33B for supporting the polish plate 33A. The polishing mechanism 33 overdrives the main chuck 17 to bring the probe 24A into contact with the polish plate 33A, thereby polishing the probe 24A. A pressure sensor 31A (e.g., load cell) is located between the support arm 32 and the support block 33B. The sensor 31A measures load that is applied to the polish plate 33A during overdrive operation. The relation between the measured load and a distortion

of the polishing mechanism 33, like the load-distortion data of the main chuck 17, is measured in advance and loaded as load-distortion data of the polishing mechanism 33 in second storage means 132.

5           As shown in FIG. 7, a controller 13 according to the present embodiment comprises first spring constant calculating means 133B, second spring constant calculating means 133C, and generated load calculating means 133D. Based on the load measured by means of  
10   the pressure sensor 31A, the first spring constant calculating means 133B obtains a spring constant  $K_P$  of the probe 24A. Based on the relation between the load and distortion of the main chuck 17, the second spring constant calculating means 133C obtains a spring  
15   constant  $K_C$  of the chuck 17. Based on the relation between the spring constant  $K_P$  of the probe 24A, the spring constant  $K_C$  of the main chuck 17, and an overdrive  $OD$  of the chuck 17, the generated load calculating means 133D obtains a generated load  $G_C$   
20   in the position of contact between the probe 24A and the chuck 17. Based on the measured load from the pressure sensor 31A and the load-distortion data of the polishing mechanism 33, as mentioned before, the controller 13 can obtain a distortion of the main chuck  
25   17 during inspection with high accuracy.

More specifically, the polish plate 33A is brought into contact with the probe 24A when a given overdrive



amounts.

Equation (4) is stored in a main chuck information storage unit 132A of the controller 13. During the inspection of the wafer W, as mentioned before, a CPU  
5 133 can obtain the generated load GC on the main chuck 17 from the overdrive OD of the chuck 17, and besides, the load GC generated according to the overdrive OD for each moment can be monitored in order. Steady inspection can be securely carried out by controlling  
10 the movement of the main chuck so that the overdrive is constant in accordance with the generated load GC.

If a probe card 24 is deformed with time, according to the present embodiment, a load reflective of the deformation of the probe card 24 can be  
15 monitored even during the inspection of the wafer W, since the generated load GC that reflects the deformation is measured. Probe cards 24 of the same type are distorted somewhat differently and cannot be guaranteed exactly the same shape. Even in this case,  
20 the load GC from the probe 24A that is applied to the polish plate 33A in the polishing mechanism 33 is measured, so that the load on the main chuck 17 that is reflective of the shape of each probe card 24 can be monitored.

25 If an unbalanced load is applied to the main chuck 17 during the inspection of the wafer W, according to the present embodiment, the load on the chuck 17 can be

monitored in the aforesaid manner. Thus, the accuracy of three-dimensional correction of the probe 24A can be improved, and the probe 24A can be securely brought into contact with an electrode pad P. In consequence, functions and effects similar to those of the foregoing embodiment can be enjoyed.

The present invention is not limited to the embodiments described above. According to the above description, the pressure sensor 31 is located between the main chuck 17 and the X-stage 18, for example. However, the pressure sensor may be set in any place that allows the load on the chuck 17 to be measured. The same applies to the pressure sensor on the polishing mechanism. After all, the probing method and the probing apparatus of the present invention comprehend any of probing methods and probing apparatuses in which load (needle pressure) from a probe that is applied to a main chuck is monitored during the inspection of wafers, the overdrive of the main chuck is controlled in accordance with the monitored load, and the position of contact of the probe is corrected three-dimensionally.

According to the present invention, as described herein, the probe can be brought accurately into contact with the electrode pad of the object of inspection even if the probe card is deformed from various causes or expanded or contracted by any thermal

effect. If the main chuck is tilted by an unbalanced load during overdrive operation, moreover, the probe can accurately touch the electrode pad of the object of inspection, so that high-accuracy inspection can be enjoyed.

Additional advantages and modifications will readily occur to those skilled in the art. Therefore, the invention in its broader aspects is not limited to the specific details and representative embodiments shown and described herein. Accordingly, various modifications may be made without departing from the spirit or scope of the general inventive concept as defined by the appended claims and their equivalents.



WHAT IS CLAIMED IS:

1. A probing method comprising steps of:  
moving a main chuck to align an object of  
inspection on the main chuck with probes of a probe  
5 card located over the main chuck;  
moving the main chuck toward the probe card,  
thereby bringing electrodes of the object of inspection  
into contact with the probes;  
overdriving the main chuck toward the probe card  
10 while measuring a load applied to the object of  
inspection by contact with the probes and controlling  
the movement of the main chuck in accordance with the  
measured load; and  
inspecting electrical properties of the object of  
15 inspection by means of the probes.
2. A probing method according to claim 1, wherein  
said control of the movement of the main chuck is  
control of an overdrive based on the measured load,  
such that the load has a given value.
- 20 3. A probing method according to claim 1 or 2,  
wherein said control of the movement of the main chuck  
includes steps of obtaining a distortion of the  
main chuck in accordance with the measured load and  
correcting at least one of dislocations between  
25 the object of inspection and the probe in X-, Y-, and  
 $\theta$ -directions in accordance with the distortion.
4. A probing method according to claim 1, wherein

002260" 2054960

said measurement of the load applied to the object of inspection by contact with the probes includes steps of locating a polishing mechanism right under the probes, the polishing mechanism including a polish plate to be used to polish the tip of the probes; moving the located polishing mechanism toward the probe card, thereby bringing the polish plate into contact with the probes; overdriving the polishing mechanism toward the probe card; and measuring a load applied to the polish plate by the probes by means of a pressure sensor attached to the polishing mechanism during the overdrive operation.

5. A probing method comprising steps of:

moving a main chuck in X-, Y-, and  $\theta$ -directions to align an object of inspection on the main chuck with probes of a probe card located over the main chuck;

moving the main chuck in a Z-direction, thereby bringing electrodes of the object of inspection into contact with the probes;

overdriving the main chuck toward the probe card while measuring a load applied to the object of inspection by contact with the probes by means of a sensor and controlling the movement of the main chuck in accordance with the measured load; and

inspecting electrical properties of the object of inspection by means of the probes.

6. A probing method according to claim 5, wherein

said sensor is located on at least one of the lower part of the main chuck and between an LM guide and an XY-stage on which the main chuck is set.

5 7. A probing method according to claim 5, wherein said control of the movement of the main chuck is control of an overdrive of the main chuck.

10 8. A probing method according to claim 5 or 7, wherein said control of the movement of the main chuck includes steps of obtaining a distortion of the main chuck in accordance with the measured load and correcting at least one of dislocations between the object of inspection and the probes in the X-, Y-, and  $\theta$ -directions in accordance with the distortion.

15 9. A probing method in which a main chuck is moved in X-, Y-, and  $\theta$ -directions to align an object of inspection on the main chuck with probes of a probe card located over the main chuck, the main chuck is moved in a Z-direction so that electrodes of the object of inspection are brought into contact with the probes, 20 the main chuck is overdriven toward the probe card, and electrical properties of the object of inspection are inspected by means of the probes, the probing method comprising steps of:

25 locating a polishing mechanism right under the probes, the polishing mechanism including a polish plate to be used to polish the tip of the probes;

moving the located polishing mechanism toward

00667502 092200

the probe card, thereby bringing the polish plate into contact with the probes;

overdriving the polishing mechanism toward the probe card;

5           measuring a load applied to the polish plate by the probes by means of a pressure sensor during the overdrive operation; and

controlling the movement of the main chuck in accordance with the measured load.

10           10. A probing method according to claim 9, wherein said sensor is set on the polishing mechanism.

11. A probing method according to claim 9, wherein said control of the movement of the main chuck is control of an overdrive of the main chuck.

15           12. A probing method according to claim 9 or 11, wherein said control of the movement of the main chuck includes steps of obtaining a distortion of the main chuck in accordance with the measured load and correcting at least one of dislocations between the  
20           object of inspection and the probes in the X-, Y-, and  $\theta$ -directions in accordance with the distortion.

13. A probing method according to claim 9, wherein said control of the overdrive of the main chuck includes steps of obtaining a distortion of the polish  
25           plate in accordance with the relation between the load applied to the polish plate and the distortion of the polish plate and the load applied to the polish plate

and measured by means of the pressure sensor; obtaining  
the spring constant of the probes from the distortion  
and an overdrive of the polish plate; obtaining the  
spring constant of the main chuck in accordance with  
5 the spring constant of the probes and the relation  
between the load and a distortion of the main chuck;  
obtaining a load applied to the main chuck by the  
probes in accordance with the spring constant of the  
main chuck and the relation between the spring constant  
10 and the overdrive of the main chuck; and controlling  
the overdrive of the main chuck in accordance with the  
obtained load.

14. A probing method according to claim 9, further  
comprising steps of obtaining a distortion of the main  
15 chuck in accordance with the load measured by means of  
the pressure sensor and correcting dislocations between  
the object of inspection and the probe in X- and  
Y-directions in accordance with the distortion.

15. A probing apparatus comprising:  
20 a main chuck carrying an object of inspection  
thereon;  
a probe card having a plurality of probes and  
located over the main chuck;  
a drive mechanism for moving the main chuck in X-,  
25 Y-, Z-, and  $\theta$ -directions;  
a pressure sensor adapted to measure a load  
applied to the object of inspection by the probes when

the drive mechanism moves the main chuck toward the probe card so that the object of inspection on the main chuck is brought into contact with probes; and

5 a controller for controlling the movement of the main chuck in accordance with a position where the probes touches the object of inspection and the load measured by means of the pressure sensor.

16. A probing apparatus comprising:

10 a main chuck carrying an object of inspection thereon;

a probe card having a plurality of probes and located over the main chuck;

a drive mechanism for moving the main chuck in X-, Y-, Z-, and  $\theta$ -directions;

15 a pressure sensor adapted to measure a load applied to the object of inspection by the probes when the drive mechanism moves the main chuck toward the probe card so that the object of inspection on the main chuck is brought into contact with the probes; and

20 a controller for obtaining a distortion of the main chuck in accordance with a position where the probes touches the object of inspection and the load measured by means of the pressure sensor.

25 17. A probing apparatus according to claim 15 or 16, wherein said controller controls an overdrive in accordance with the measured load so that the load has a given value.

18. A probing apparatus according to claim 16,  
wherein said controller corrects at least one of  
dislocations between the object of inspection and the  
probes in the X-, Y-, and  $\theta$ -directions in accordance  
5 with the distortion.

19. A probing apparatus comprising:

a main chuck carrying an object of inspection  
thereon;

10 a polishing mechanism having a polish plate and  
attached to the main chuck;

a probe card having a plurality of probes and  
located over the main chuck;

a drive mechanism for moving the main chuck in X-,  
Y-, Z-, and  $\theta$ -directions;

15 a pressure sensor adapted to measure a load  
applied to the polish plate of the polishing mechanism  
attached to the main chuck by the probes when the drive  
mechanism moves the main chuck toward the probe card so  
that the polish plate is brought into contact with the  
20 probes; and

a controller for controlling the drive mechanism,  
the controller including a mechanism for obtaining the  
spring constant of the probes in accordance with the  
load measured by means of the pressure sensor,  
25 obtaining the spring constant of the main chuck in  
accordance with the relation between the load and a  
distortion of the main chuck, and obtaining a load

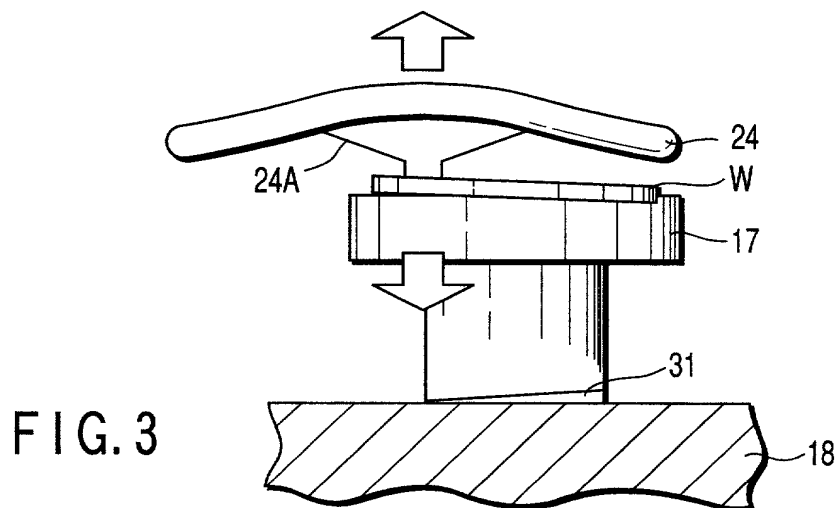
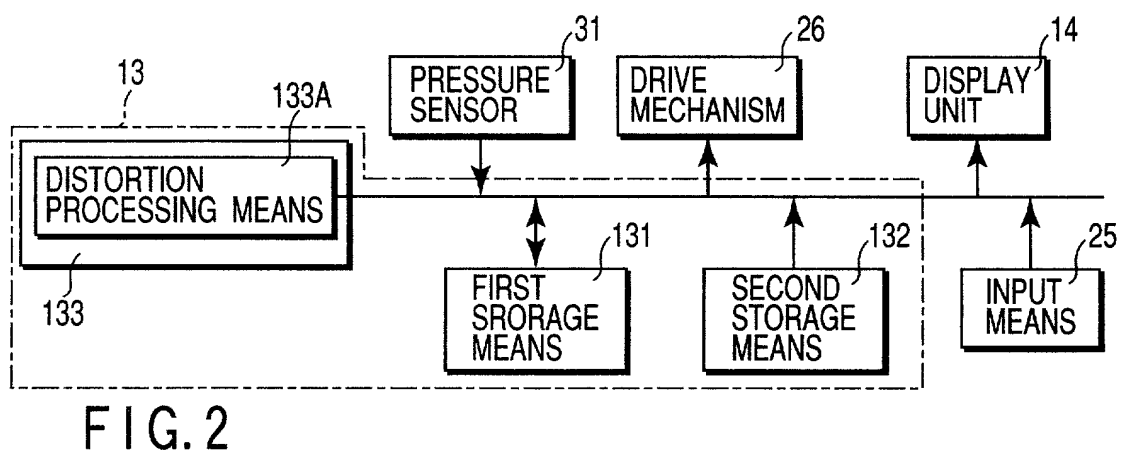
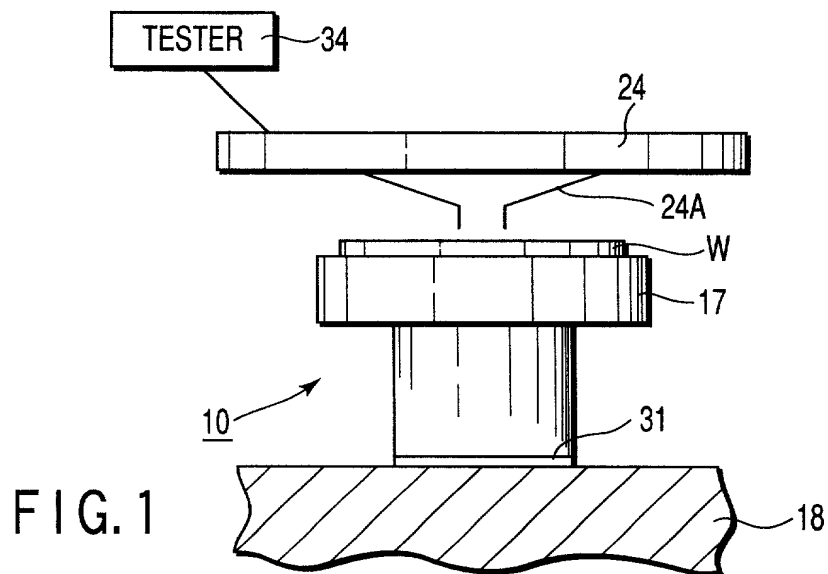
**BOOK REVIEW**

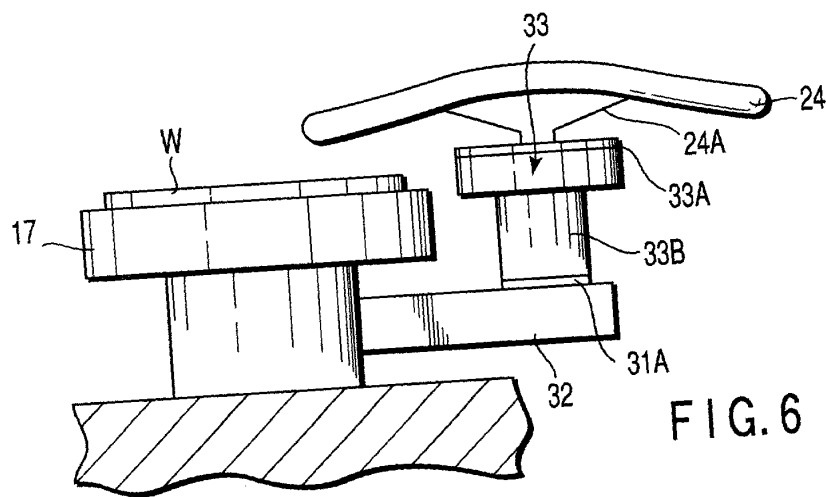
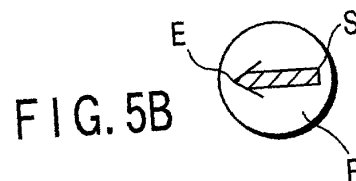
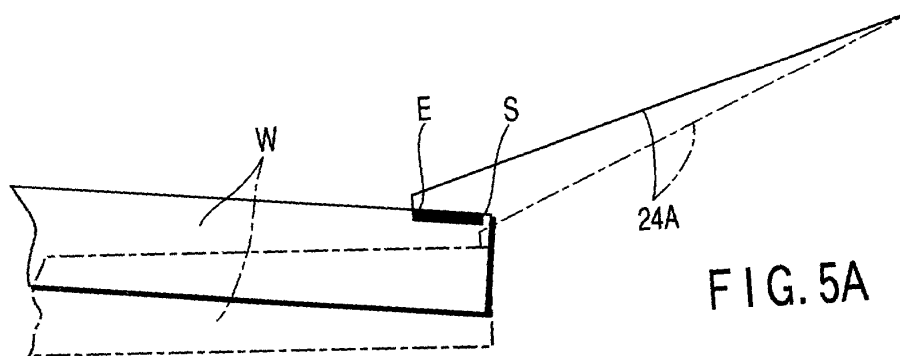
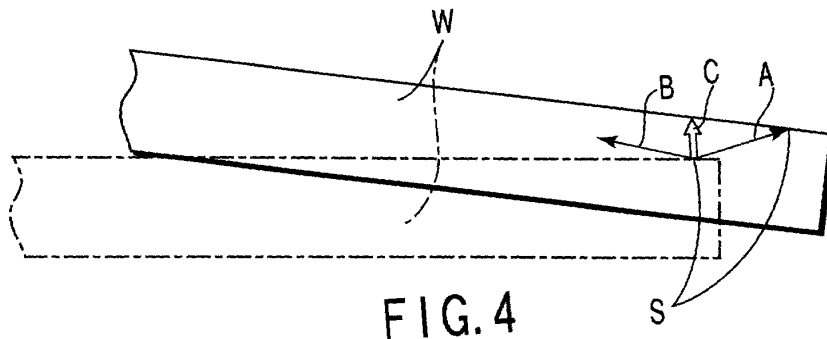


ABSTRACT OF THE DISCLOSURE

Disclosed is a probing method comprising steps of moving a main chuck to align an object of inspection on the main chuck with probes of a probe card located over the main chuck, moving the main chuck toward the probe card, thereby bringing electrodes of the object of inspection into contact with the probes, overdriving the main chuck toward the probe card while measuring a load applied to the object of inspection by contact with the probes and controlling the movement of the main chuck in accordance with the measured load, and inspecting the electrical properties of the object of inspection by means of the probes.

002260 20579960





002260-20529960

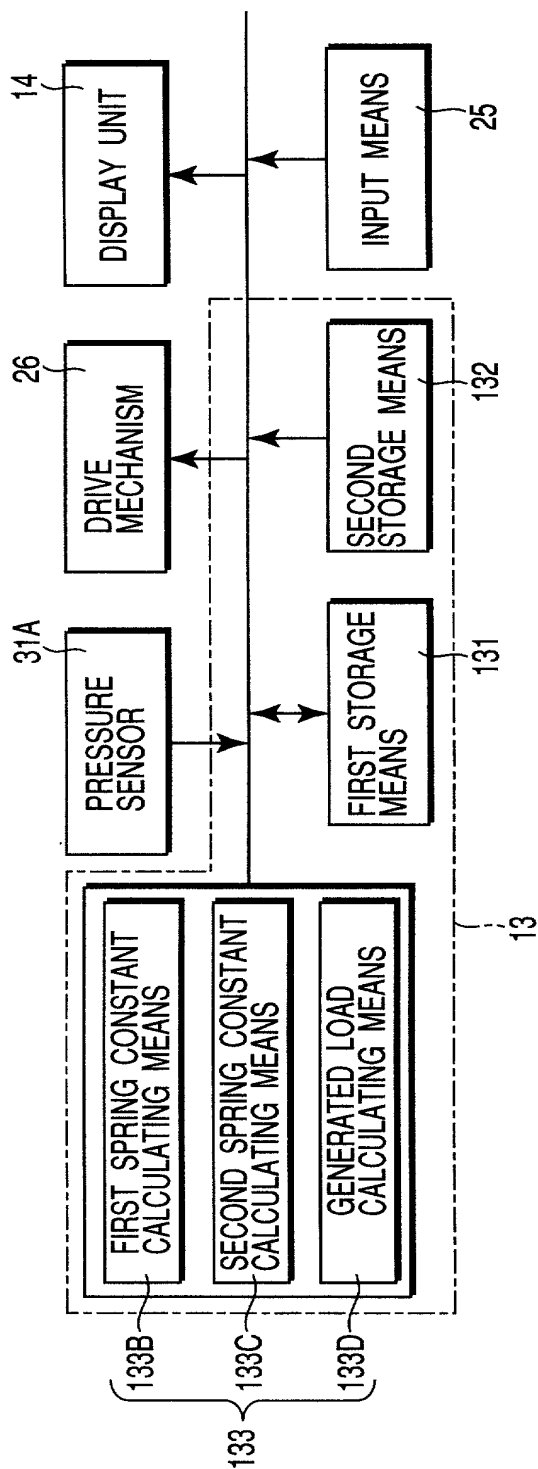


FIG. 7

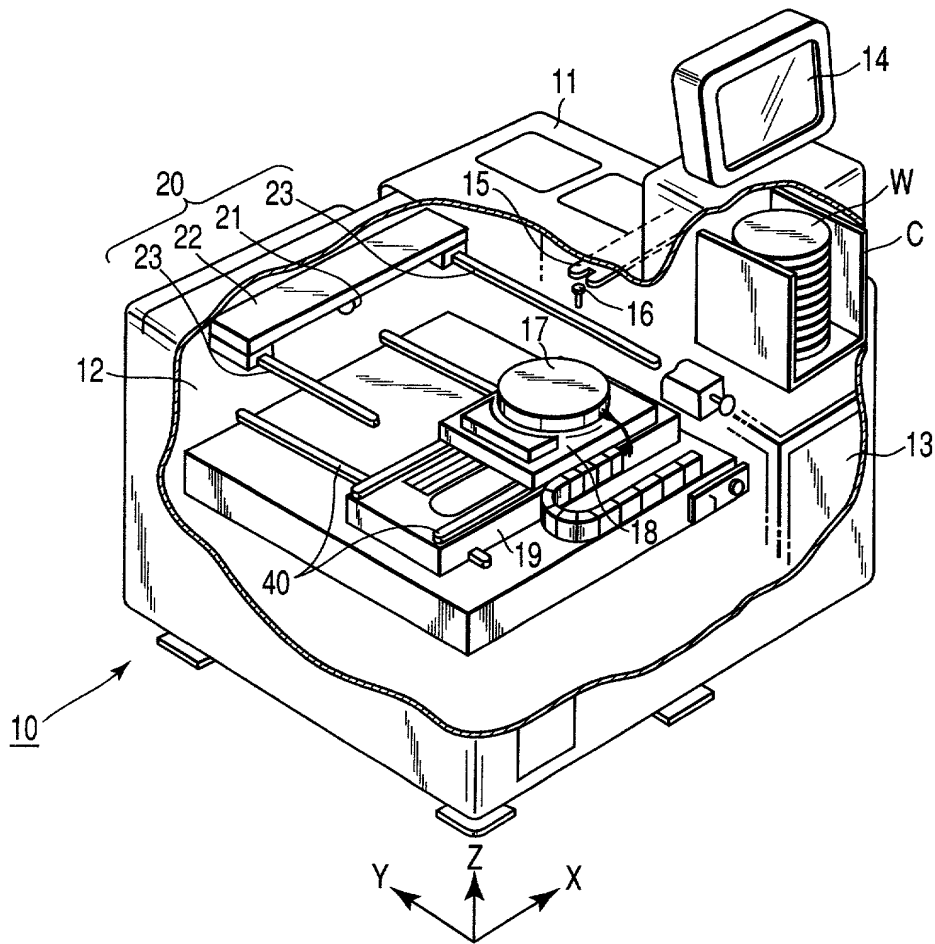


FIG. 8 PRIOR ART

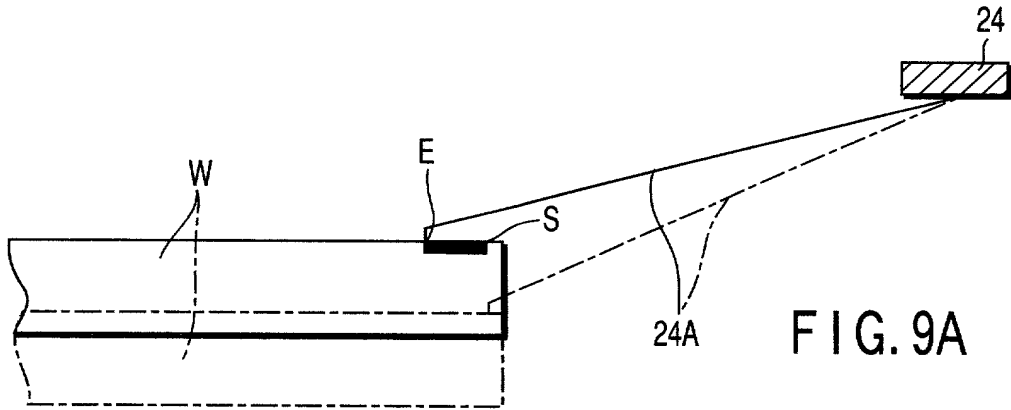


FIG. 9A

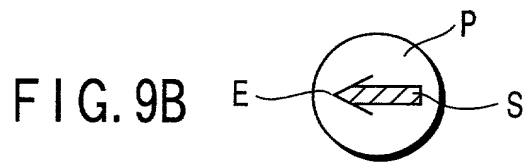


FIG. 9B

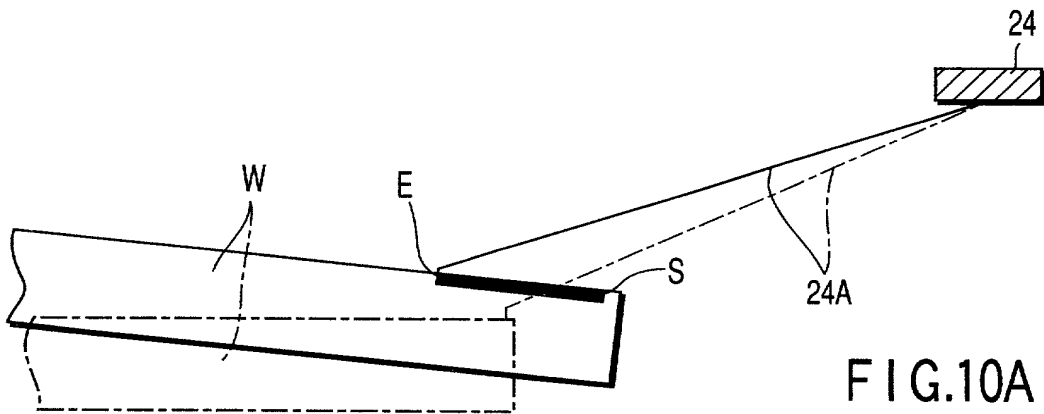


FIG. 10A

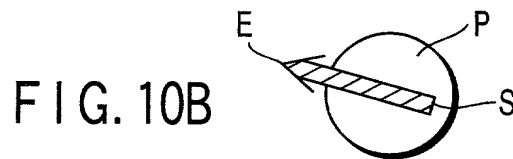


FIG. 10B

002260" 20529960

# Declaration Power of Attorney For Patent Application

## 特許出願宣言

### Japanese Language Declaration

私は、下欄に氏名を記載した発明として、以下の通り宣言する：

As a below named inventor, I hereby declare that:

私の住所、郵便の宛先および国籍は、下欄に氏名に続いて記載したとおりであり、

My residence, post office address and citizenship are as stated below next to my name,

名称の発明に関し、請求の範囲に記載した特許を求める主題の本来の、最初にして唯一の発明者である（一人の氏名のみが下欄に記載されている場合）か、もしくは本来の、最初にして共同の発明者である（複数の氏名が下欄に記載されている場合）と信じ、

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

プローブ方法及びプローブ装置

PROBING METHOD AND PROBING APPARATUS

その明細書を  
（該当するほうに印を付す）

The specification of which  
(check one)

☐ ここに添付する。

☐ is attached hereto.

☐ \_\_\_\_\_月 \_\_\_\_\_日に

☐ was filed on \_\_\_\_\_

as Application Serial No.

出願番号第 \_\_\_\_\_ 号として

\_\_\_\_\_ and was amended on

提出し、 \_\_\_\_\_ 月 \_\_\_\_\_ 日に補正した。

\_\_\_\_\_

（該当する場合）

(if applicable)

私は、前記のとおり補正した請求の範囲を含む前記明細書の内容を検討し、理解したことを陳述する。

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

私は、連邦規則法典第37部第1章第56条（a）項に従い、本願の審査に所要の情報を開示すべき義務を有することを認める。

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

## Japanese Language Declaration

私は、合衆国法典第35部第119条、第172条、又は第365条に基づく下記の外国特許出願又は発明者証出願の外国優先権利益を主張し、さらに優先権の主張に係わる基礎出願の出願日前の出願日を有する外国特許出願又は発明者証出願を以下に明記する：

I hereby claim foreign priority benefits under Title 35, United States Code Sec. 119, Sec. 172 or Sec. 365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior foreign application(s)  
先の外国出願

			Priority Claimed 優先権の主張	
11-285139 (Number) (番号)	JAPAN (Country) (国名)	06/10/1999 (Day/Month/Year Filed) (出願年月日)	<input checked="" type="checkbox"/> Yes あり	<input type="checkbox"/> No なし
			<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>
			<input type="checkbox"/>	<input type="checkbox"/>

私は、合衆国法典第35部第120条に基づく下記の合衆国特許出願の利益を主張し、本願の請求の範囲各項に記載の主題が合衆国法典第35部第112条第1項に規定の態様で先の合衆国出願に開示されていない限度において、先の出願の出願日と本願の国内出願日又はPCT国際出願日の間に公表された連邦規則法典第37部第1章第56条(a)項に記載の所要の情報を開示すべき義務を有することを認める。

I hereby claim the benefit of Title 35, United States Code, Sec. 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Sec. 112, I acknowledge the duty to disclose any material information as defined in Title 37, Code of Federal Regulations, Sec. 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application No.) (出願番号)	(Filing Date) (出願日)	(Status: Patented, Pending, Abandoned) (現況: 特許許可済、係属中、放棄済)
(Application No.) (出願番号)	(Filing Date) (出願日)	(Status: Patented, Pending, Abandoned) (現況: 特許許可済、係属中、放棄済)

私は、ここに自己の知識に基づいて行った陳述がすべて真実であり、自己の有する情報及び信ずるところに従って行った陳述で真実であると信じ、更に故意に虚偽の陳述等を行った場合、合衆国法典第18部第1001条により、罰金もしくは禁固に処せられるか、又はこれらの刑が併科され、又はかかる故意による虚偽の陳述が本願ないし本願に対して付与される特許の有効性を損なうことがあることを認識して、以上の陳述を行ったことを宣言する。

I hereby declare that all statements made herein of my own knowledge are true; and further that all statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

002260 " 205/9500



# Japanese Language Declaration

(日本語宣言書)

委任状：私は、下記の発明者として、本出願に関する一切の  
手続を米特許商標局に対して遂行する弁理士または代理人  
として、下記の者を指名いたします。  
(弁理士、または代理人の氏名及び登録番号を明記のこと)

POWER OF ATTORNEY: As a named inventor, I  
hereby appoint the following attorney(s) and/or  
agent(s) to prosecute this application and transact  
all business in the Patent and Trademark Office  
connected therewith. (list name and registration  
number)

And I hereby appoint Norman F. Oblon (Reg. No. 24,618), Marvin J. Spivak (Reg. No. 24,913), C. Irvin McClelland (Reg. No. 21,124), Gregory J. Maier (Reg. No. 25,599), Arthur I. Neustadt (Reg. No. 24,854), Richard D. Kelly (Reg. No. 27,757), James D. Hamilton (Reg. No. 28,421), Eckhard H. Kuesters (Reg. No. 28,870), Robert T. Pous (Reg. No. 29,099), Charles L. Gholz (Reg. No. 26,395), Vincent J. Sunderdick (Reg. No. 29,004), William E. Beaumont (Reg. No. 30,996), Robert F. Gnuse (Reg. No. 27,295), Jean-paul Lavalleye (Reg. No. 31,451), Stephen G. Baxter (Reg. No. 32,884), Robert W. Hahl (Reg. No. 33,893), Richard L. Treanor (Reg. No. 36,379), Steven P. Weihrouch (Reg. No. 32,829), John T. Goolkasian (Reg. No. 26,142), Richard L. Chinn (Reg. No. 34,305), Steven E. Lipman (Reg. No. 30,011), Carl E. Schlier (Reg. No. 34,426), James J. Kulbaski (Reg. No. 34,648), Richard A. Neifeld (Reg. No. 35,299), J. Derek Msaon (Reg. No. 35,270), Surinder Sachar (Reg. No. 34,423), Christina M. Gadiano (Reg. No. 37,628), Jeffrey B. McIntyre (Reg. No. 36,867), Paul E. Rauch (Reg. No. 38,591), William T. Enos (Reg. No. 33,128) and Michael E. McCabe, Jr., (Reg. No. 37,182) each of whose address is Fourth Floor, 1755 Jefferson Davis Highway, Arlington, Virginia 22202, or any one of them, my attorneys with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent & Trademark Office connected therewith, and request that correspondence be directed to Oblon, Spivak, McClelland, Maier & Neustadt, P.C., Fourth Floor, 1755 Jefferson Davis Highway, Arlington, Virginia 22202.

書類送付先：

Send Correspondence to  
Oblon, Spivak, McClelland,  
Maier & Neustadt, P.C.,  
  
Fourth Floor,  
1755 Jefferson Davis Highway,  
Arlington, Virginia 22202

直通電話連絡先：

Direct Telephone Calls to: (name and telephone number)  
Telephone No. (703) 413-3000  
Facsimile No. (703) 413-2220

唯一のまたは第一発明者の氏名 小林 将人	Full name of sole or first inventor Masahito Kobayashi
同発明者の署名 日付	Inventor's signature Date August 31, 2000 <i>Masahito Kobayashi</i>
住 所 日本国府中市	Residence Fuchu-shi, Japan
国 籍 日本	Citizenship JAPAN
郵便の宛先 〒107-8481 日本国東京都港区赤坂5丁目3番6号	Post Office Address c/o Intellectual Property Dept., TOKYO ELECTRON LIMITED
東京エレクトロン株式会社 知的財産部内	3-6 Akasaka 5-chome, Minato-ku, Tokyo 107-8481, Japan

(第二以降の共同発明者に対しても同様に記載し、署名を  
すること。)

(Supply similar information and signature for second  
and subsequent joint inventors.)

002260"205/9960

# Japanese Language Declaration

(日本語宣言書)

第 2 共同発明者の氏名 (該当する場合)	Full name of 2nd joint inventor, if any
石井 一成	Kazunari Ishii
同第 2 発明者の署名 日付	2nd inventor's signature Date
	Kazunari Ishii September 5, 2000
住 所	Residence
日本国韭崎市	Nirasaki-shi, Japan
国 籍	Citizenship
日本	JAPAN
郵便の宛先 〒107-8481 日本国東京都港区赤坂5丁目3番6号	Post Office Address c/o Intellectual Property Dept., TOKYO ELECTRON LIMITED
東京エレクトロン株式会社 知的財産部内	3-6 Akasaka 5-chome, Minato-ku, Tokyo 107-8481, Japan
第 共同発明者の氏名 (該当する場合)	Full name of joint inventor, if any
同第 発明者の署名 日付	inventor's signature Date
住 所	Residence
国 籍	Citizenship
郵便の宛先	Post Office Address
第 共同発明者の氏名 (該当する場合)	Full name of joint inventor, if any
同第 発明者の署名 日付	inventor's signature Date
住 所	Residence
国 籍	Citizenship
郵便の宛先	Post Office Address

002250"2052950